

**60A 650V Trench Fieldstop IGBT with anti-parallel diode SRE60N065FSU2DG**
**General Description**

The SRE60N065FSU2DG is a Field Stop Trench IGBT with anti-parallel diode, which offers ultra-low switching losses, high energy efficiency for switching applications such as PFC, Power Supply, Inverter, etc.

The SRE60N065FSU2DG package is TO-247.

**Features**

- High Breakdown Voltage to 650V
- Advanced Trench Fieldstop technology
  - Smooth Switching Off with Lower Spike
  - High Ruggedness, Temperature Stability
  - Easy Parallel Switching Capability due to Positive Temperature Coefficient in  $V_{CE(SAT)}$
- LOW  $V_{CE(SAT)}$
- Enhanced Avalanche Capability
- Non-Automotive Qualified

**Application**

- Inverter
- Uninterruptible power supplies
- PFC application
- Converter with high switching frequency

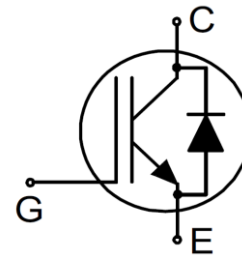
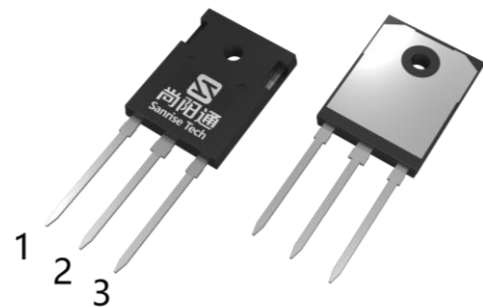
**Symbol**


Figure 1 Symbol of SRE60N065FSU2DG

**Package Type**


TO-247

- Pin 1- gate
- Pin 2-&backside-collector
- Pin 3-emitter

Figure 2 Package Type of SRE60N065FSU2DG

**Ordering Information**

SRE60N065FSU2DG □ □ - □

Circuit Type			
Package			
T: TO-247			

G: Green  
 Blank: Tube  
 TR: Tape & Reel

Package	Part Number	Marking ID	Packing Type
TO-247	SRE60N065FSU2DGT-G1	SRE60N065FSU2DGTG1	Tube

**60A 650V Trench Fieldstop IGBT with anti-parallel diode SRE60N065FSU2DG**
**Absolute Maximum Ratings**

Parameter		Symbol	Rating	Unit
Collector-emitter Voltage		$V_{CES}$	650	V
Gate-emitter Voltage		$V_{GES}$	$\pm 20$	V
Transient Gate-emitter Voltage			$\pm 30$	V
Continuous Collector Current	$T_C=25^\circ\text{C}$	$I_C$	120	A
	$T_C=100^\circ\text{C}$		60	
Pulsed Collector Current, Limited by $T_{Jmax}$		$I_{CM}$	240	A
Diode Continuous Collector Current	$T_C=25^\circ\text{C}$	$I_F$	70	A
	$T_C=100^\circ\text{C}$		$40^{(1)}$	
Diode Pulsed Current, Limited by $T_{Jmax}$		$I_{FM}$	120	A
Power Dissipation	$T_C=25^\circ\text{C}$	$P_{tot}$	306	W
	$T_C=100^\circ\text{C}$		153	
Operating Junction Temperature Range		$T_J$	$-40 \sim 175^{(2)}$	$^\circ\text{C}$
Storage Temperature Range		$T_{STG}$	$-55 \sim 150$	$^\circ\text{C}$
Lead Temperature (Soldering, 10 sec)		$T_{LEAD}$	260	$^\circ\text{C}$

Note:

1. Current level is limited by  $T_{j\_max}$ .
2. Reliability testing conducted at  $T_{Jmax}=175^\circ\text{C}$ .

**Thermal Resistance**

Parameter	Symbol	Min.	Typ.	Max.	Unit
IGBT Thermal Resistance, Junction-to-Case	$R_{thJC}$	-	-	0.49	$^\circ\text{C}/\text{W}$
Diode Thermal Resistance, Junction-to-Case	$R_{thJC}$	-	-	1.0	
Thermal Resistance, Junction-to-Ambient	$R_{thJA}$	-	-	40	

**60A 650V Trench Fieldstop IGBT with anti-parallel diode SRE60N065FSU2DG**
**Electrical Characteristics**

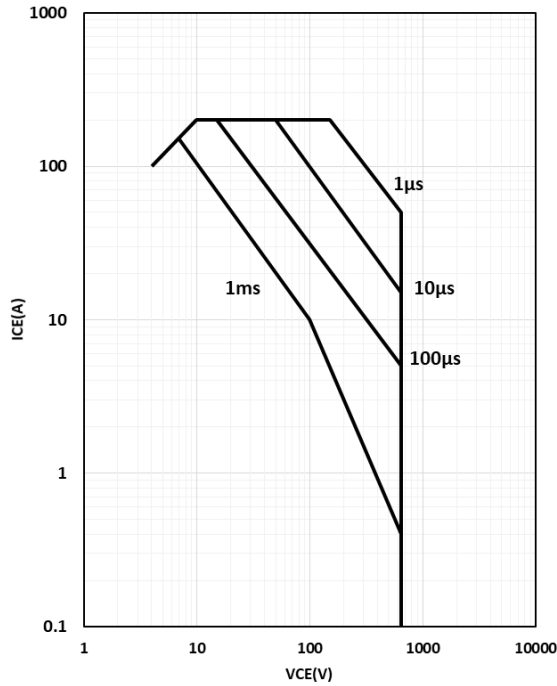
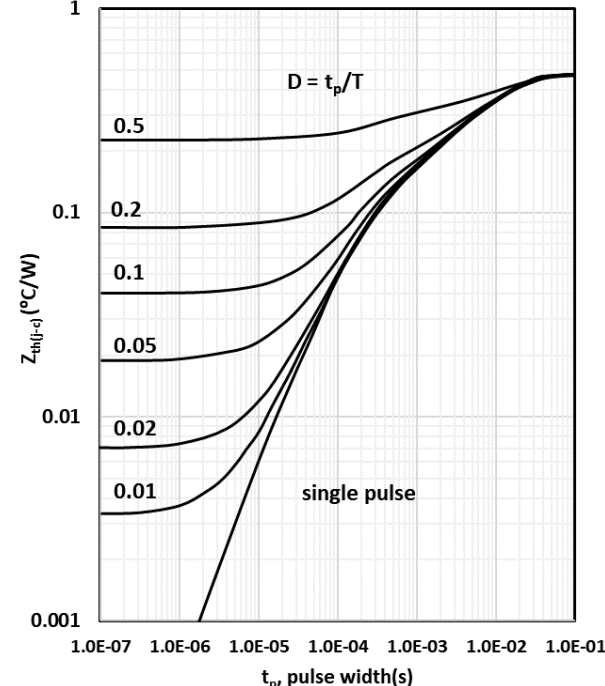
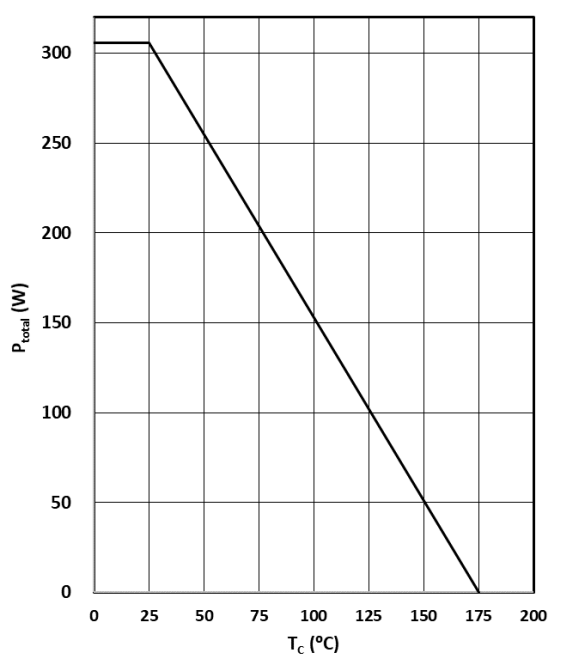
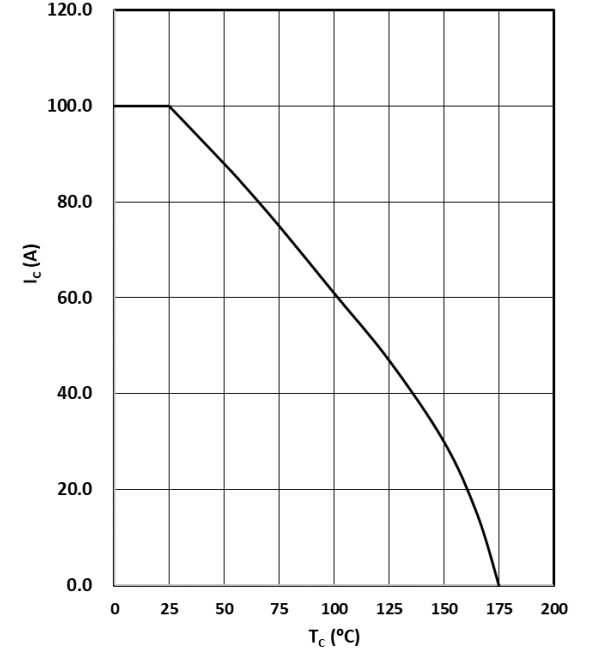
 T<sub>J</sub> = 25°C, unless otherwise specified.

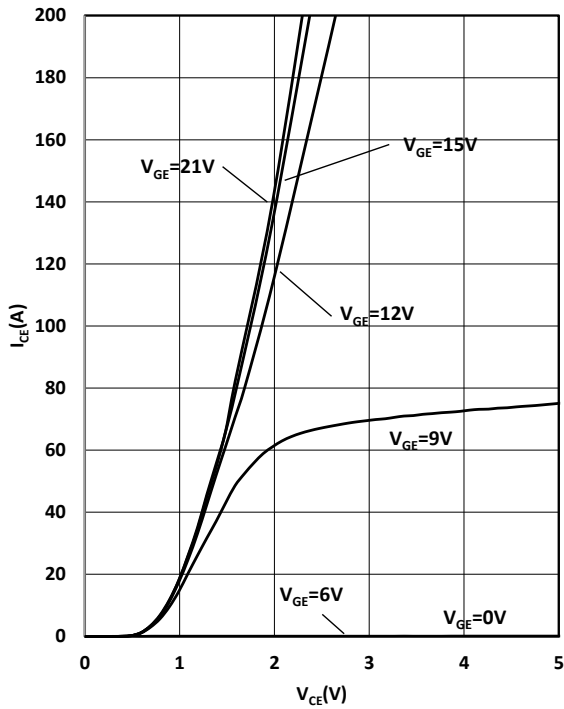
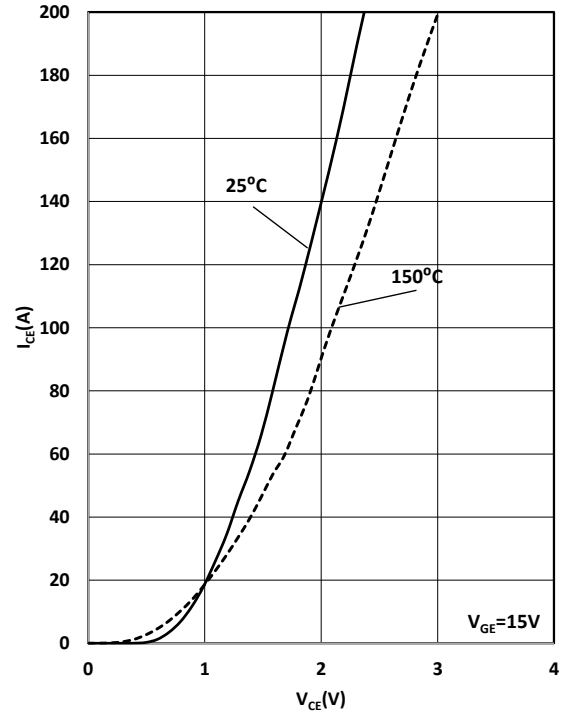
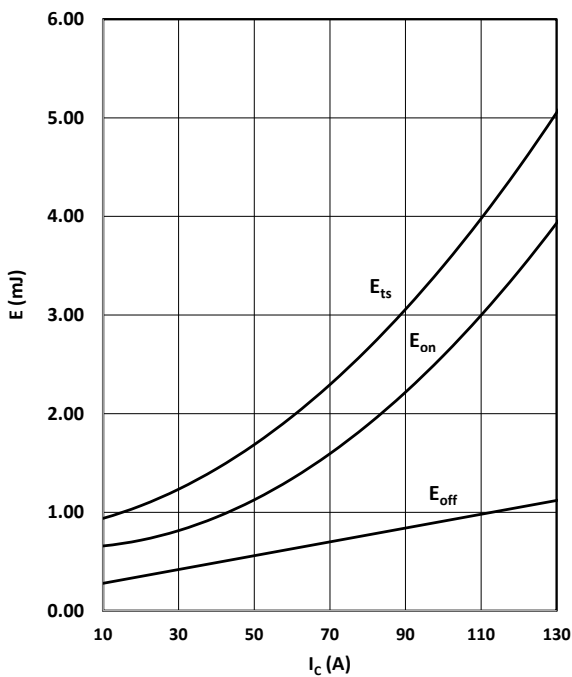
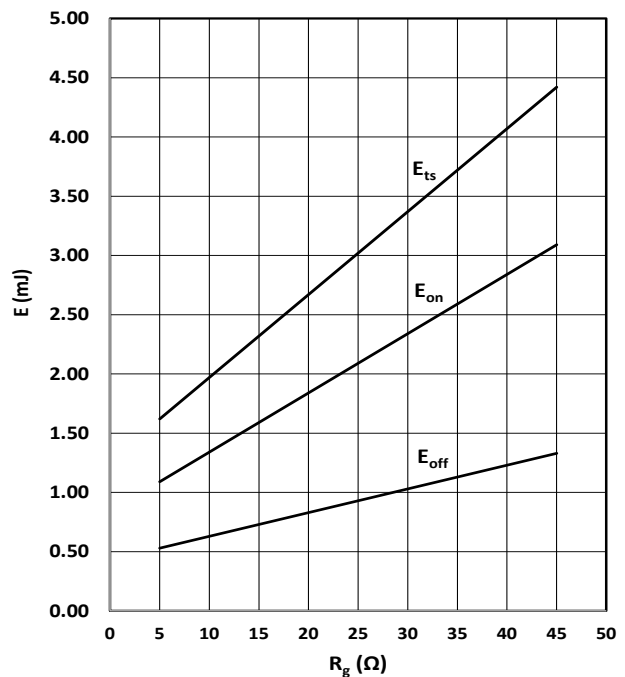
Parameter		Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
<b>Statistic Characteristics</b>								
Collector-emitter Voltage	Breakdown	BV <sub>CES</sub>	V <sub>GE</sub> =0V, I <sub>C</sub> =250μA	650			V	
Gate Threshold Voltage		V <sub>GE(th)</sub>	V <sub>CE</sub> =V <sub>GE</sub> , I <sub>C</sub> =250μA	4.2	4.8	5.4	V	
Collector-emitter saturation voltage		V <sub>CEsat</sub>	V <sub>GE</sub> =15V, I <sub>C</sub> =60A, T <sub>J</sub> =25°C	1.45	1.51	1.68	V	
			T <sub>J</sub> =125°C		1.81		V	
			T <sub>J</sub> =175°C		2.02		V	
Zero Gate Voltage Collector Current		I <sub>CES</sub>	V <sub>CE</sub> =650V, V <sub>GE</sub> =0V T <sub>J</sub> =25°C		0.1	40	μA	
			T <sub>J</sub> =175°C			1	mA	
Gate-emitter Leakage Current	Forward	I <sub>GESF</sub>	V <sub>GE</sub> =20V, V <sub>CE</sub> =0V			100	nA	
	Reverse	I <sub>GESR</sub>	V <sub>GE</sub> =-20V, V <sub>CE</sub> =0V			-100	nA	
<b>Dynamic Characteristics</b>								
Input Capacitance		C <sub>IES</sub>	V <sub>CE</sub> =25V, V <sub>GE</sub> =0V, f=100KHz		2460		pF	
Output Capacitance		C <sub>OES</sub>			247			
Reverse Transfer Capacitance		C <sub>RES</sub>			48			
Gate Resistance		R <sub>G</sub>	f=1 MHz, Open Drain		1.7		Ω	
Turn-on Delay Time		t <sub>d(on)</sub>	T <sub>J</sub> =25°C V <sub>CC</sub> =400V, I <sub>C</sub> =60A R <sub>G</sub> =10Ω, V <sub>GE</sub> =0/15V Energy losses include "tail" and diode reverse recovery		21		ns	
Rise Time		t <sub>r</sub>			38		ns	
Turn-off Delay Time		t <sub>d(off)</sub>			122		ns	
Fall Time		t <sub>f</sub>			70		ns	
Turn-on energy		E <sub>on</sub>			1.34		mJ	
Turn-off energy		E <sub>off</sub>			0.63		mJ	
Total switching energy		E <sub>ts</sub>			1.97		mJ	
Turn-on Delay Time		t <sub>d(on)</sub>		T <sub>J</sub> =150°C V <sub>CC</sub> =400V, I <sub>C</sub> =60A R <sub>G</sub> =10Ω, V <sub>GE</sub> =0/15V Energy losses include "tail" and diode reverse recovery		18		ns
Rise Time		t <sub>r</sub>				39		ns
Turn-off Delay Time		t <sub>d(off)</sub>				149		ns
Fall Time		t <sub>f</sub>			118		ns	
Turn-on energy		E <sub>on</sub>			2.43		mJ	
Turn-off energy		E <sub>off</sub>			0.92		mJ	
Total switching energy		E <sub>ts</sub>			3.35		mJ	
Gate to Emitter Charge		Q <sub>GE</sub>	V <sub>CC</sub> =400V, I <sub>C</sub> =60A V <sub>GE</sub> =0 to 15V			28		nC
Gate to Collector Charge		Q <sub>GC</sub>			91			
Gate Charge Total		Q <sub>G</sub>			190			

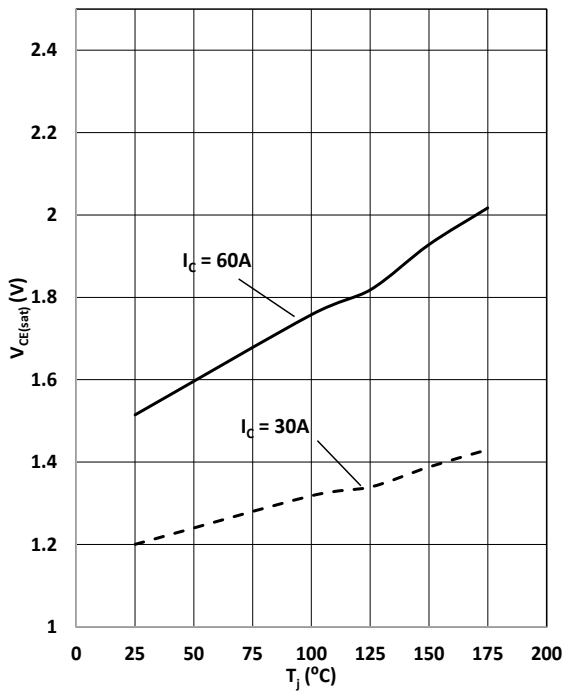
**60A 650V Trench Fieldstop IGBT with anti-parallel diode SRE60N065FSU2DG**

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Reverse Diode Characteristics</b>						
Diode Forward Voltage	$V_F$	$I_F=30A$ $T_J=25^\circ C$		1.61	1.89	V
		$I_F=30A$ $T_J=125^\circ C$		1.44		
		$I_F=30A$ $T_J=175^\circ C$		1.34		
		$I_F=60A$ $T_J=25^\circ C$		1.89	2.22	V
		$I_F=60A$ $T_J=125^\circ C$		1.79		
		$I_F=60A$ $T_J=175^\circ C$		1.68		
Reverse Recovery Time	$t_{rr}$	$T_J=25^\circ C$ $V_R=400V, I_F=30A$ $dI_F/dt=1100A/us$		130		ns
Reverse Recovery Charge	$Q_{rr}$			0.72		uC
Peak Reverse Recovery Current	$I_{rrm}$			18		A
Diode peak rate of fall of reverse Recovery current during tb	$dI_{rr}/dt$			-456		A/us
Reverse Recovery Time	$t_{rr}$	$T_J=25^\circ C$ $V_R=400V, I_F=60A$ $dI_F/dt=1000A/us$		179		ns
Reverse Recovery Charge	$Q_{rr}$			0.84		uC
Peak Reverse Recovery Current	$I_{rrm}$			19		A
Diode peak rate of fall of reverse Recovery current during tb	$dI_{rr}/dt$			-375		A/us
Reverse Recovery Time	$t_{rr}$	$T_J=150^\circ C$ $V_R=400V, I_F=30A$ $dI_F/dt=1100A/us$		143		ns
Reverse Recovery Charge	$Q_{rr}$			1.34		nC
Peak Reverse Recovery Current	$I_{rrm}$			25		A
Diode peak rate of fall of reverse Recovery current during tb	$dI_{rr}/dt$			-523		A/us
Reverse Recovery Time	$t_{rr}$	$T_J=150^\circ C$ $V_R=400V, I_F=60A$ $dI_F/dt=1000A/us$		223		ns
Reverse Recovery Charge	$Q_{rr}$			1.93		uC
Peak Reverse Recovery Current	$I_{rrm}$			26		A
Diode peak rate of fall of reverse Recovery current during tb	$dI_{rr}/dt$			-394		A/us

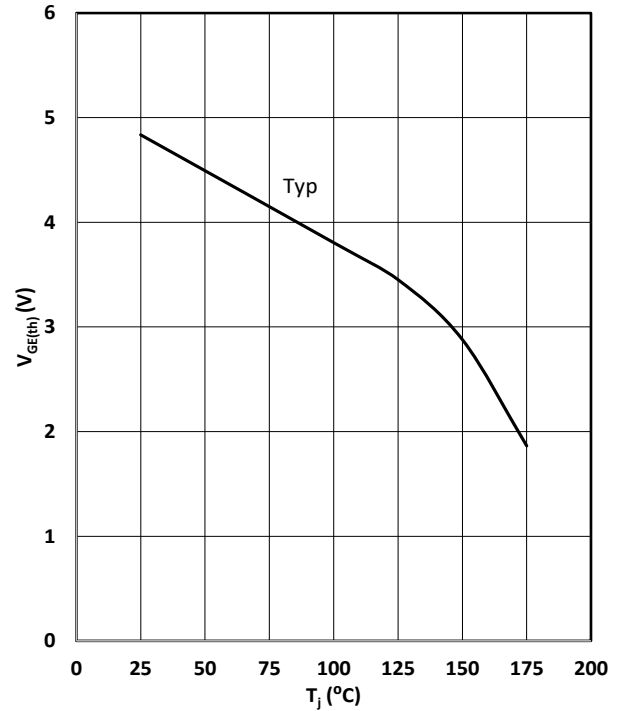
**Typical Performance Characteristics**

<p><b>Figure 3: IGBT FBSOA</b></p>  <p><math>I_C = f(V_{CE}); V_{GE} \geq 15/0V; T_j \leq 175^\circ C</math></p>	<p><b>Figure 4: IGBT transient thermal impedance</b></p>  <p><math>R_{th(j-c)} = f(t_p); \text{ duty cycle: } D = t_p/T</math></p>
<p><b>Figure 5: Power dissipation</b></p>  <p><math>P_{tot} = f(T_c);</math></p>	<p><b>Figure 6: Collector current vs. temperature</b></p>  <p><math>I_c = f(T_j); V_{GE} \geq 15V; T_j \leq 175^\circ C</math></p>

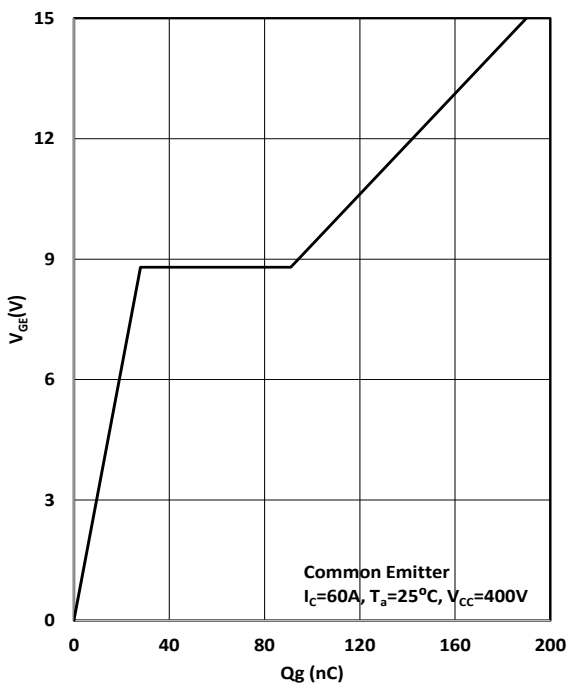
**60A 650V Trench Fieldstop IGBT with anti-parallel diode SRE60N065FSU2DG**
**Figure 7: Typical Output Characteristics**

 $I_C = f(V_{CE}); T_j = 25^\circ\text{C}; \text{parameter: } V_{GE}$ 
**Figure 8: Typical transfer characteristic**

 $I_C = f(V_{CE}); T_j = 25^\circ\text{C vs } 150^\circ\text{C}$ 
**Figure 9: Typical switching energy losses as a function of collector current**

 $E = f(I_C); V_{CE} = 400\text{V}; T_j = 25^\circ\text{C}; R_G = 10\Omega$ 
**Figure 10: Typical switching energy losses as a function of gate resistor**

 $E = f(R_G); V_{CE} = 400\text{V}; T_j = 25^\circ\text{C}; I_C = 60\text{A}$

**60A 650V Trench Fieldstop IGBT with anti-parallel diode SRE60N065FSU2DG**
**Figure 11: Typical collector-emitter saturation voltage as a function of junction temperature**


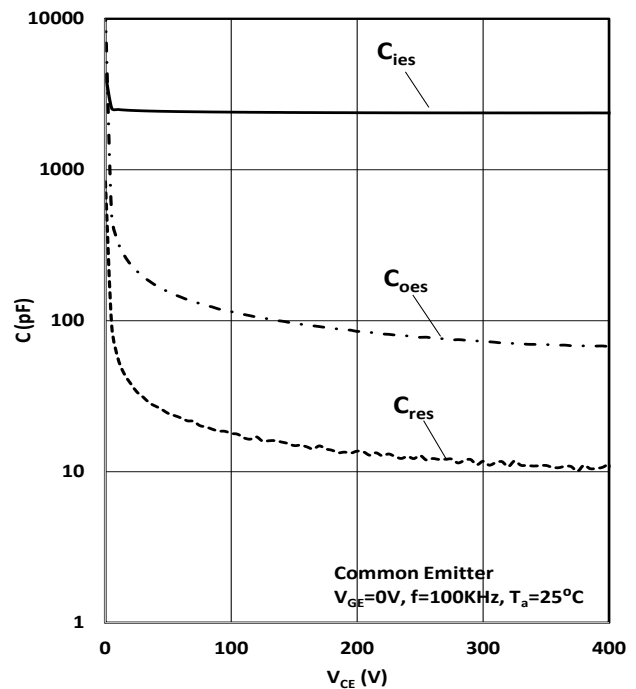
$$V_{CE} = f(T_j); V_{GE} = 15V$$

**Figure 12: Gate-emitter threshold voltage as a function of junction temperature**


$$V_{GE} = f(T_j); I_{CE} = 250\mu A$$

**Figure 13: Typical Gate Charge**


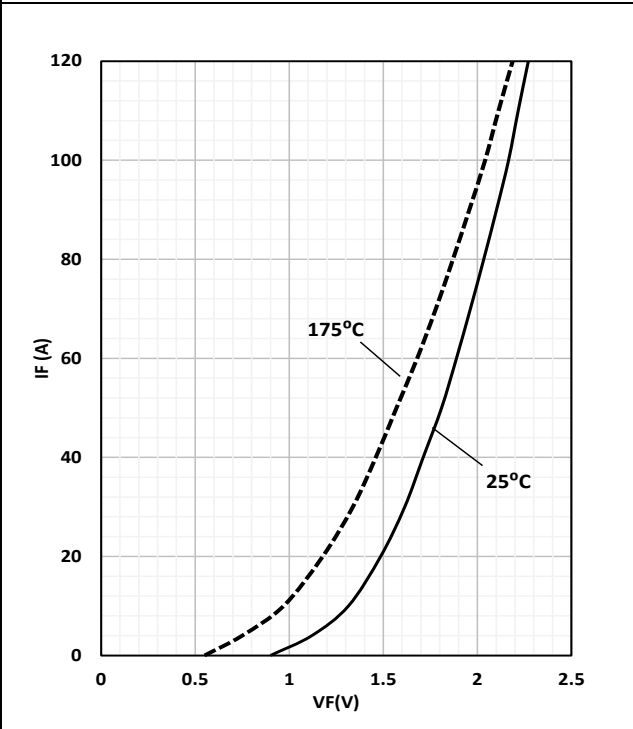
$$V_{GE} = f(Q_{gate}); I_C = 60A$$

**Figure 14: Typical Capacitances**


$$C = f(V_{CE}); V_{GE} = 0; f = 100KHz$$

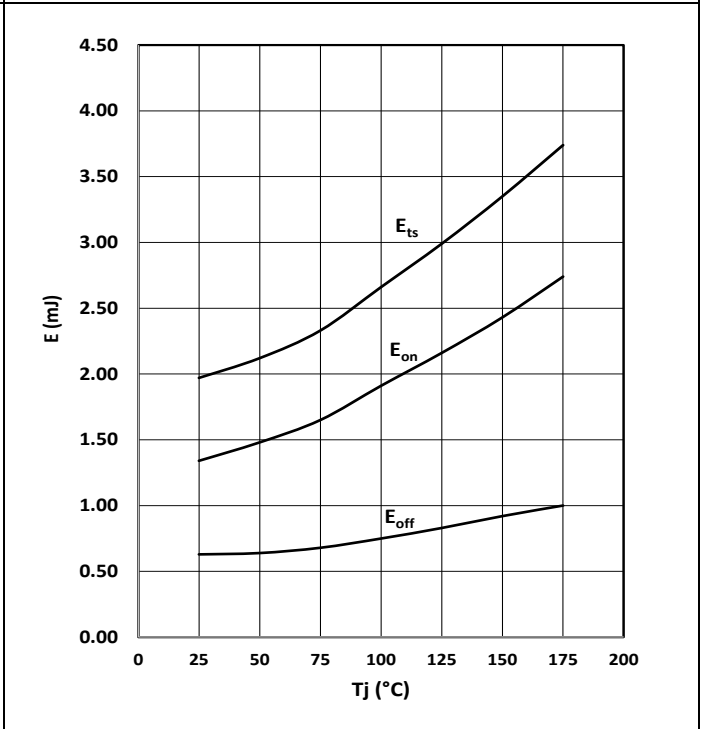
**60A 650V Trench Fieldstop IGBT with anti-parallel diode SRE60N065FSU2DG**

Figure 15: Typical diode forward current as a function of forward voltage



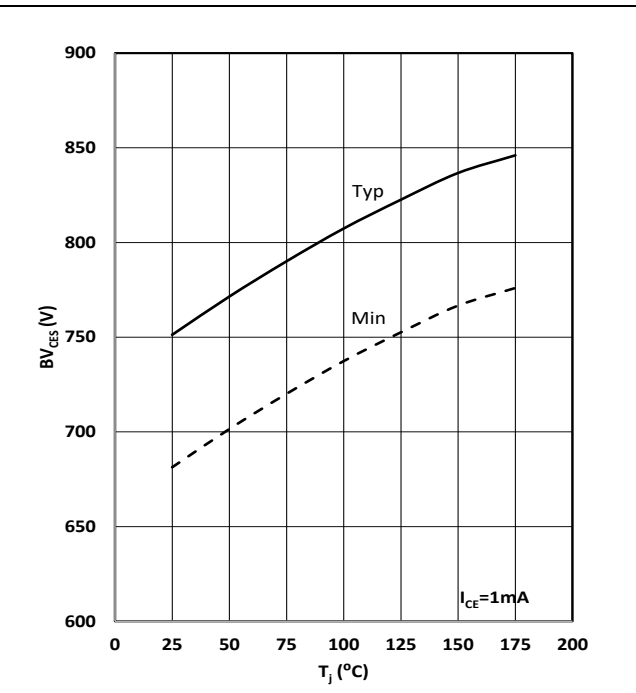
$I_F = f(V_{EC});$

Figure 16: Typical switching energy losses as a function of junction temperature



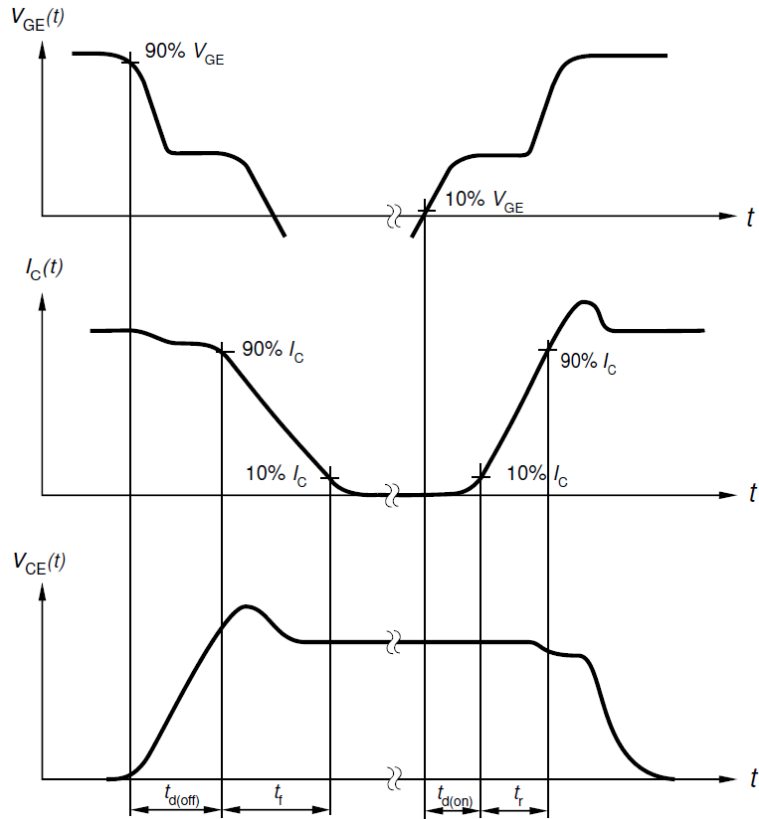
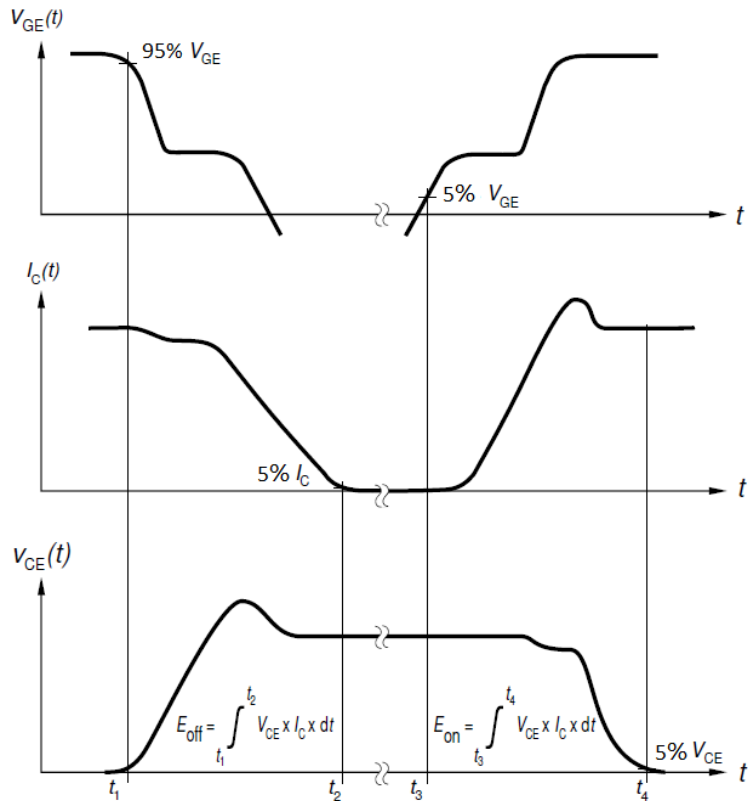
$E = f(T_j); V_{CE} = 400V; I_c = 60A; R_G = 10\Omega$

Figure 17: Collector-emitter Breakdown Voltage vs. temperature

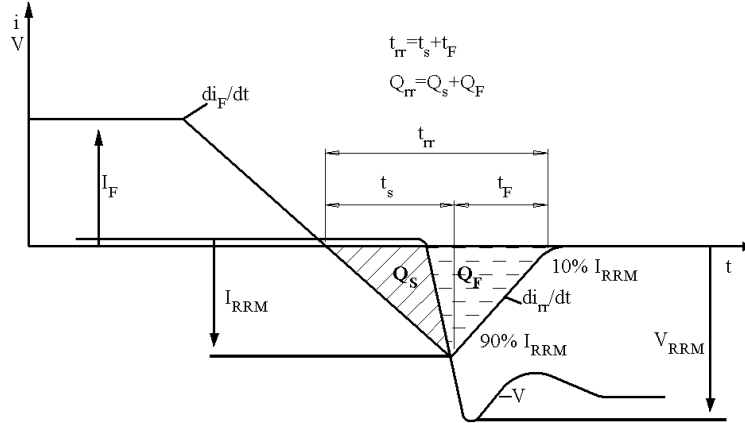


$BV_{ces} = f(T_j);$

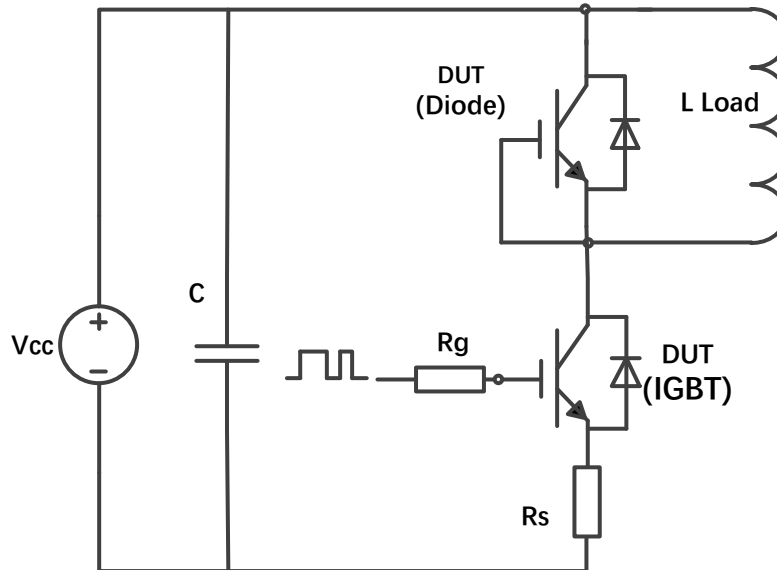


**Test Circuits**
**1. Definition Switching times**

**2. Definition Switching losses**


**3. Definition Diode Switching Characteristics**



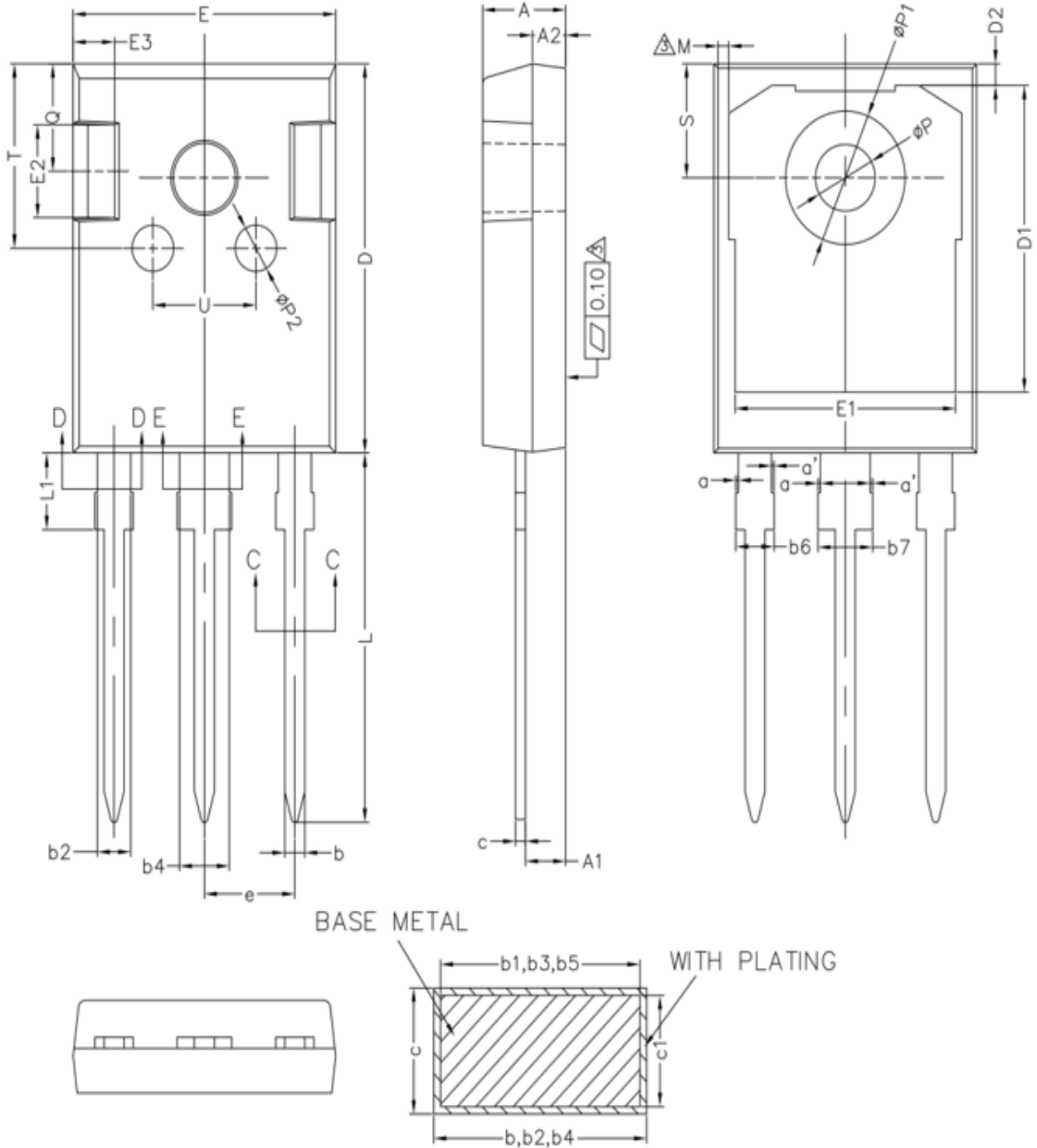
**4. Dynamic test circuit**



**Mechanical Dimensions**

**TO-247**

**Unit: mm**



**Mechanical Dimensions**

Symbol	Dimensions(mm)			Symbol	Dimensions(mm)		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.90	5.00	5.10	D2	1.05	1.20	1.35
A1	2.31	2.41	2.51	E	15.70	15.80	15.90
A2	1.90	2.00	2.10	E1	13.10	13.30	13.50
a	0	-	0.15	E2	4.90	5.00	5.10
a'	0	-	0.15	E3	2.40	2.50	2.60
b	1.16	-	1.26	e	5.34	5.44	5.54
b1	1.15	1.2	1.22	L	19.80	19.92	20.10
b2	1.96	-	2.06	L1	-	-	4.30
b3	1.95	2.00	2.02	M	0.35	-	0.95
b4	2.96	-	3.06	P	3.50	3.60	3.70
b5	2.95	3.00	3.02	P1	7.00	-	7.40
b6	-	-	2.25	P2	2.40	2.50	2.60
b7	-	-	3.25	Q	5.60	-	6.00
c	0.59	-	0.66	S	6.05	6.15	6.25
c1	0.58	0.60	0.62	T	9.80	-	10.20
D	20.90	21.00	21.10	U	6.00	-	6.40
D1	16.25	16.55	16.85	-	-	-	-



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